



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	30-10-2023
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	MDG MD CHAMPION	<b>Representative Title</b>	MDG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST33KTPM2I3WBZA9	517M*T4ABZA9	A	997G	30-10-2023
Amount		UoM	Unit type	ST ECOPACK Grade
48.00		mg	Each	ECOPACK® 2
Comment		ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information					
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles			
1	260	3	 life.augmented		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy			Comment
Not Applicable; if coating is used or other bulk termination	Matte Tin	Copper Alloy			

Package Designator	Size	Nbr of instances	Shape	
EQFN	5x5x0.55mm	32		
Comment	Package : B0EY UFQFPN32 5X5X0.55 WF DM00716940			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	517M*4ABZA9				6000000.0	1000001.3
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	1.420	mg	supplier	die	Silicon (Si)	7440-21-3		1.267	mg	892254	26396
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	12676	375
				supplier	metallization	Copper (Cu)	7440-50-8		0.057	mg	40141	1188
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.009	mg	6338	188
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1408	42
				supplier	Passivation	Silicon Oxide	7631-86-9		0.067	mg	47183	1396
Leadframe-C7025-Ag	Copper & its alloys	20.267	mg	supplier	Alloy	Cu	7440-50-8		19.264	mg	950500	401325
				supplier	Alloy	Ni	7440-02-0		0.608	mg	30000	12667
				supplier	Alloy	Si	7440-21-3		0.132	mg	6500	2744
				supplier	Alloy	Mg	7439-95-4		0.030	mg	1500	633
				supplier	coating	Ag	7440-22-4		0.233	mg	11500	4856
Glue - 8600	M-011 Other inorganic materials	0.763	mg	supplier	Glue	Silver	7440-22-4		0.622	mg	815000	12961
				supplier	Glue	[Octahydro-4,7-methano-1H-indenediy]bis(m	42594-17-2		0.046	mg	60000	954
				supplier	Glue	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl met	7534-94-3		0.046	mg	60000	954
				supplier	Glue	Isobornyl acrylate	5888-33-5		0.046	mg	60000	954
				supplier	Glue	2-(3,4-Epoxy cyclohexyl)ethyltrimethoxysilane	3388-04-3		0.004	mg	5000	80
Bonding wire- Au wire (2N)	M-011 Other inorganic materials	0.740	mg	supplier	Bonding wire	Au	7440-57-5		0.732	mg	990000	15260
				supplier	Bonding wire	Pd	7440-05-3		0.007	mg	10000	154
Encapsulation - EME-G700LTD	M-011 Other inorganic materials	23.020	mg	supplier	Molding compound	Epoxy Resin	Proprietary		1.151	mg	49998	23978
				supplier	Molding compound	Phenol Resin	Proprietary		0.622	mg	26999	12948
				supplier	Molding compound	Silica (Amorphous)A	60676-86-0		20.028	mg	870005	417244
				supplier	Molding compound	Silica (Amorphous)B	7631-86-9		1.151	mg	49998	23978
				supplier	Molding compound	Carbon Black	1333-86-4		0.069	mg	3000	1439
External plating - Matte Tin	M-011 Other inorganic materials	1.790	mg	supplier	Matte tin	Tin	7440-31-5		1.790	mg	1000000	37287